

Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application.

1. (currently amended) A polymeric PTC thermistor comprising:

a conductive member comprising a conductive polymer having PTC characteristics; and

two electrodes each placed in two different locations on the conductive member;

wherein the conductive member and at least one of the two electrodes are bonded via an adhesive which has conductivity and which deteriorates in an overheated state in a temperature range in which the conductive polymer thermally expands and irreversibly increases the electrical resistance.

2. (withdrawn) A circuit protection method that includes a component that generates heat through the flow of excessive current, comprising:

providing a PTC thermistor in the circuit; and

bonding a wiring which composes the circuit to the component in such a way as to allow current to flow using an adhesive which has conductivity and which deteriorates in an overheated state and irreversibly increases the electrical resistance.

3. (previously presented) A thermistor according to claim 1, wherein both of the two electrodes are bonded via the adhesive.

4. (previously presented) A thermistor according to claim 1, wherein one of the two electrodes is bonded to the conductive member via a weld.

5. (previously presented) A thermistor according to claim 1, wherein one of the two electrodes is bonded to the conductive member via solder.

6. (canceled)

7. (canceled)
8. (previously presented) A thermistor according to claim 1, wherein the adhesive comprises a thermoplastic resin.
9. (previously presented) A thermistor according to claim 8, wherein the thermoplastic resin comprises vinyl acetate resin, polyvinyl alcohol resin, acrylic resin, vinyl urethane resin, or mixtures thereof.
10. (previously presented) A thermistor according to claim 1, wherein the adhesive comprises a thermosetting resin.
11. (previously presented) A thermistor according to claim 10, wherein the thermosetting resin comprises urea resin, melamine resin, phenol resin, resorcinol resin, epoxy resin, silicone resin, α -olefin maleic acid anhydride resin, polyamide resin, polyimide resin, or mixtures thereof.
12. (previously presented) A thermistor according to claim 1, wherein the adhesive comprises a conductive powder.
13. (previously presented) A thermistor according to claim 12, wherein the conductive powder comprises gold, silver, nickel, or copper.
14. (withdrawn) A method according to claim 2, wherein the component comprises a battery.
15. (withdrawn) A method according to claim 14, wherein the battery is a lithium battery comprising a positive electrode and a negative electrode.
16. (withdrawn) A method according to claim 15, wherein the wiring is bonded to the positive electrode by means of the adhesive.
17. (withdrawn) A method according to claim 16, wherein the negative electrode is connected to the circuit by welding or soldering.
18. (withdrawn) A method according to claim 2, wherein the component comprises a capacitor.